

KOREAN PATENT ABSTRACTS

(11)Publication number: 1020010113521 A
(43)Date of publication of application: 28.12.2001

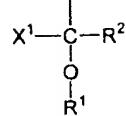
(21)Application number: 1020010034122 (71)Applicant: INTERNATIONAL BUSINESS
(22)Date of filing: 16.06.2001 MACHINES CORPORATION
JSR CORPORATION
(30)Priority: 16.06.2000 1 (72)Inventor: ITO HIROSHI
KAJITA TORU
NISHIMURA YUKIO
SHIMOKAWA TSUTOMU
YAMAHARA NOBORU
YAMAMOTO MASAFUMI

(51)Int. Cl G03F 7/004

(54) RADIATION SENSITIVE RESIN COMPOSITION

(57) Abstract:

PURPOSE: Provided is a radiation sensitive resin composition which exhibits high transmittance of radiation, high sensitivity, resolution, and pattern shape, and which can produce semiconductors at a high yield without deteriorating a resolution. CONSTITUTION: The radiation sensitive resin composition comprises an acid-labile group containing resin and a photoacid generator. The resin has a structure of the formula 1. In the formula 1, R1 represents a hydrogen atom, a monovalent acid-labile group, an alkyl group having 1-6 carbon atoms which does not have an acid-labile group, or an alkylcarbonyl group having 2-7 carbon atoms which does not have an acid-labile group, X1 represents a linear or branched fluorinated alkyl group having 1-4 carbon atoms, and R2 represents a hydrogen atom, a linear or branched alkyl group having 1-10 carbon atoms, or a linear or branched fluorinated alkyl group having 1-10 carbon atoms.



copyright KIPO 2002

Legal Status

Date of request for an examination (20060417)

Notification date of refusal decision (00000000)

Final disposal of an application (registration)

Date of final disposal of an application (20070927)

Patent registration number (1007775200000)

Date of registration (20071112)

Number of opposition against the grant of a patent ()

Date of opposition against the grant of a patent (00000000)

Number of trial against decision to refuse ()

Date of requesting trial against decision to refuse ()

Date of extinction of right ()